

REMARKS

Careful consideration has been given by the applicants to the Examiner's comments and rejection of the claims, as set forth in the outstanding Office Action, and favorable reconsideration and allowance of the application, as amended, is earnestly solicited.

Applicants note the Examiner's rejection of the claims under 35 U.S.C. §112, second paragraph for being indefinite in that the claims contain process limitations which do not incorporate structural aspects. Accordingly, in order to clearly obviate this particular ground of formal rejection, applicants have amended the terminology of the claims to indicate the positive structural aspects with regard to the combination of the laminate support and the circuit device, which in this instance is a circuit pad of large-scale integrated circuitry.

The foregoing formal amendments should clearly and unambiguously provide appropriate terminology pertaining to the claims.

Applicants further note the Examiner's rejection of Claims 1, 6, 7 and 12 under 35 U.S.C. §103(a), as being unpatentable over previously cited Japanese JP 11-107,112 for the reasons detailed in that Office Action.

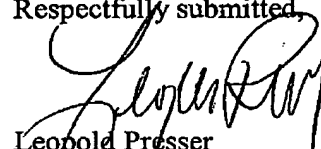
However, applicants respectfully take issue with the Examiner in that regard, noting that the particular fiberglass woven mesh of the support structure is not at all disclosed in the Japanese publication and, in particular, the Japanese fails to provide the specific spacings between the strands of the mesh, whereby the separation distances are such that during wire bonding of a wire onto the circuit pad or the circuit structure, the pad will be supported in a manor so as to be prevented from collapse, the latter of which is a condition of which at times is encountered during the wire bonding process.

The foregoing was also recognized in connection with the parent application, which has already matured into U.S. Patent No. 6,488,198 B1, and wherein it has been recognized that the particular spacings or separation distances of the woven fiberglass mesh of the support is deemed to provide novel distinctions over the art.

This particular structure is not at all disclosed in the Japanese publication, although the latter discloses a glass mesh structure. However, the specific distances, which are also correlated with the diameters of the wires which are being wire bonded to the circuit pad cannot in any manner be ascertained from the Japanese publication, nor are they suggested therein. It remained for the present applicants to inventively derive the particular correlation between the wire diameters and the separation distances of the closed woven mesh of the fiberglass support, which will prevent collapse of the circuits or circuit pads during wire bonding. Accordingly, in order to further emphasize the foregoing, the claims have been amended so as to set forth these particular aspects in a clear and precise manner.

In view of the foregoing comments and amendments, applicants respectfully submit that the claims clearly and unambiguously distinguish over the prior art and the early and favorable reconsideration of the claims and allowance of the application by the Examiner is earnestly solicited. However, in the event that the Examiner has any queries concerning the instantly submitted Amendment, applicants' attorney respectfully requests that he be accorded the courtesy of possibly a telephone conference to discuss any matters in need of attention.

Respectfully submitted,


Leopold Presser
Registration No.: 19,827
Attorney for Applicants

Scully, Scott, Murphy & Presser
400 Garden City Plaza - Suite 300
Garden City, New York 11530
(516) 742-4343

LP:jj